Notification about the transfer of the semiconductor business

The semiconductor business of Panasonic Corporation was transferred on September 1, 2020 to Nuvoton Technology Corporation (hereinafter referred to as "Nuvoton"). Accordingly, Panasonic Semiconductor Solutions Co., Ltd. became under the umbrella of the Nuvoton Group, with the new name of Nuvoton Technology Corporation Japan (hereinafter referred to as "NTCJ").

In accordance with this transfer, semiconductor products will be handled as NTCJ-made products after September 1, 2020. However, such products will be continuously sold through Panasonic Corporation.

Publisher of this Document is NTCJ.

If you would find description "Panasonic" or "Panasonic semiconductor solutions", please replace it with NTCJ.

Except below description page
 "Request for your special attention and precautions in using the technical information and semiconductors described in this book"

Nuvoton Technology Corporation Japan

Revision. 1

MOS FET

FC4B21320L

Panasonic

FC4B21320L

Gate resistor installed Dual N-channel MOS FET

For lithium-ion secondary battery protection circuits

■ Features

- Source-source ON resistance:Rss(on) typ. = 36 m Ω (VGS = 4.5 V)
- CSP(Chip Size Package)
- RoHS compliant (EU RoHS / MSL:Level 1 compliant)

■ Marking Symbol: 2D

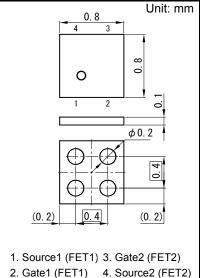
■ Packaging

Embossed type (Thermo-compression sealing): 20 000 pcs / reel (standard)

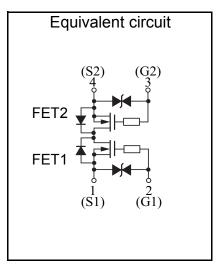
■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Source-source Voltage	VSS	12	V
Gate-source Voltage	VGS	±8	V
Source Current (DC)	IS *1	2.5	Α
Source Guiterit (DG)	IS *2	4	Α
Source Current (Pulsed)	ISp *3	25	Α
Total Power Dissipation	PD *1	0.34	W
Total I owel Dissipation	PD *2	0.9	W
Channel Temperature	Tch	150	°C
Storage Temperature Range	Tstg	-55 to +150	°C
Thermal Resistance (ch-a)	Rth *1	368	°C/W
Thermal Resistance (ch-a)	Rth *2	139	°C/W

- Note *1 Mounted on FR4 board ($25.4 \text{ mm} \times 25.4 \text{ mm} \times t1.0 \text{ mm}$) using the minimum recommended pad size (36 μ m Copper).
 - *2 Mounted on Ceramic substrate (70 mm \times 70 mm \times t1.0 mm).
 - *3 $t = 10 \mu s$, Duty Cycle $\leq 1 \%$



Panasonic	XLGA004-W-0808-RA
JEITA	_
Code	_



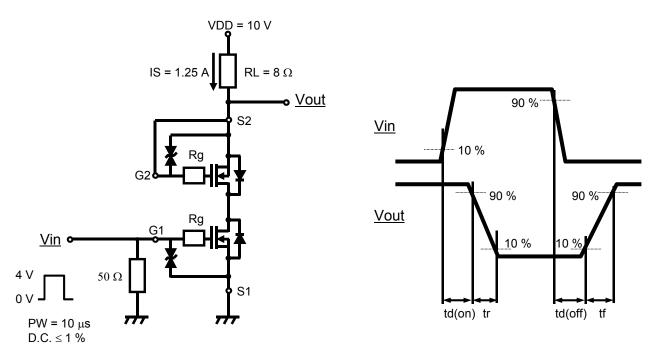
■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Source-source Breakdown Voltage	VSSS	IS = 1 mA, VGS = 0 V	12			V
Zero Gate Voltage Source Current	ISSS	VSS = 12 V, VGS = 0 V			1.0	μΑ
Gate-source Leakage Current	IGSS	VGS = ±8 V, VSS = 0 V			±10	μА
	1000	VGS = ± 5 V, VSS = 0 V			±1.0	
Gate-source Threshold Voltage	Vth	IS = 0.07 mA, VSS = 10 V	0.35	0.9	1.4	V
Source-source On-state Resistance	RSS(on)1	IS = 1.25 A, VGS = 4.5 V	27	36	48	mΩ
		IS = 1.25 A, VGS = 3.8 V	29	39	53	
	RSS(on)3	IS = 1.25 A, VGS = 3.1 V	32	45	75	
	RSS(on)4	IS = 1.25 A, VGS = 2.5 V	35	58	115	
Body Diode Forward Voltage	VF(s-s)	IF = 1.25 A, VGS = 0 V		0.6	1.2	V
Input Capacitance *1	Ciss			205		pF
Output Capacitance *1	Coss	VSS = 10 V, VGS = 0 V, f = 1 MHz		50		
Reverse Transfer Capacitance *1	Crss			40		i
Turn-on delay Time *1,*2	td(on)	VDD = 10 V, VGS = 0 to 4.0 V		0.10		0
Rise Time *1,*2	tr	IS = 1.25 A		0.15		μS
Turn-off delay Time *1,*2	td(off)	VDD = 10 V, VGS = 4.0 to 0 V		0.50		μS
Fall Time *1,*2	tf	IS = 1.25 A		0.30		
Total Gate Charge *1	Qg	VDD = 10 V		3.5		
Gate-source Charge *1	Qgs	VGS = 0 to 4.0 V,		8.0		nC
Gate-drain Charge *1	Qgd	IS = 1.25 A		1.0		

Note Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

- *1 Guaranteed by design, not subject to production testing
- *2 Measurement circuit for Turn-on Delay Time / Rise Time / Turn-off Delay Time / Fall Time

Note2:Measurement circuit

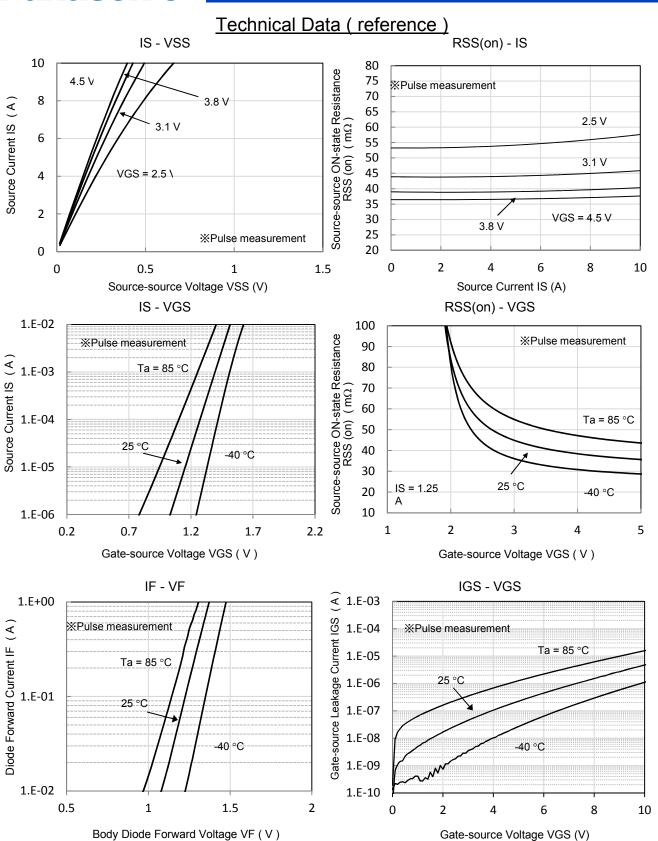


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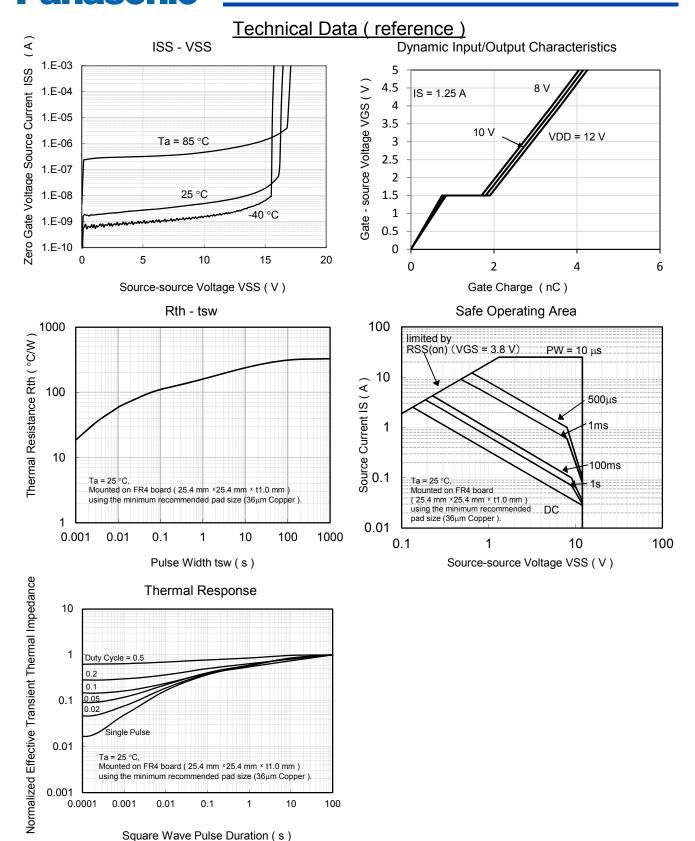
MOS FET FC4B21320L



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MOS FET

FC4B21320L

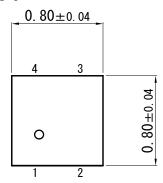


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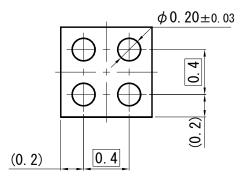
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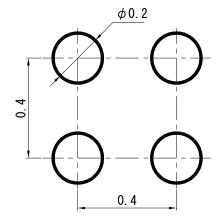
Unit: mm







■ Land Pattern (Reference) (Unit: mm)



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